



MULTI-CHIP ELECTRONIC PACKAGE AND COOLING SYSTEM

Paul A. Farrar et al.

Appl. No.: 09/945,024 Atty Docket: MICRON.246A

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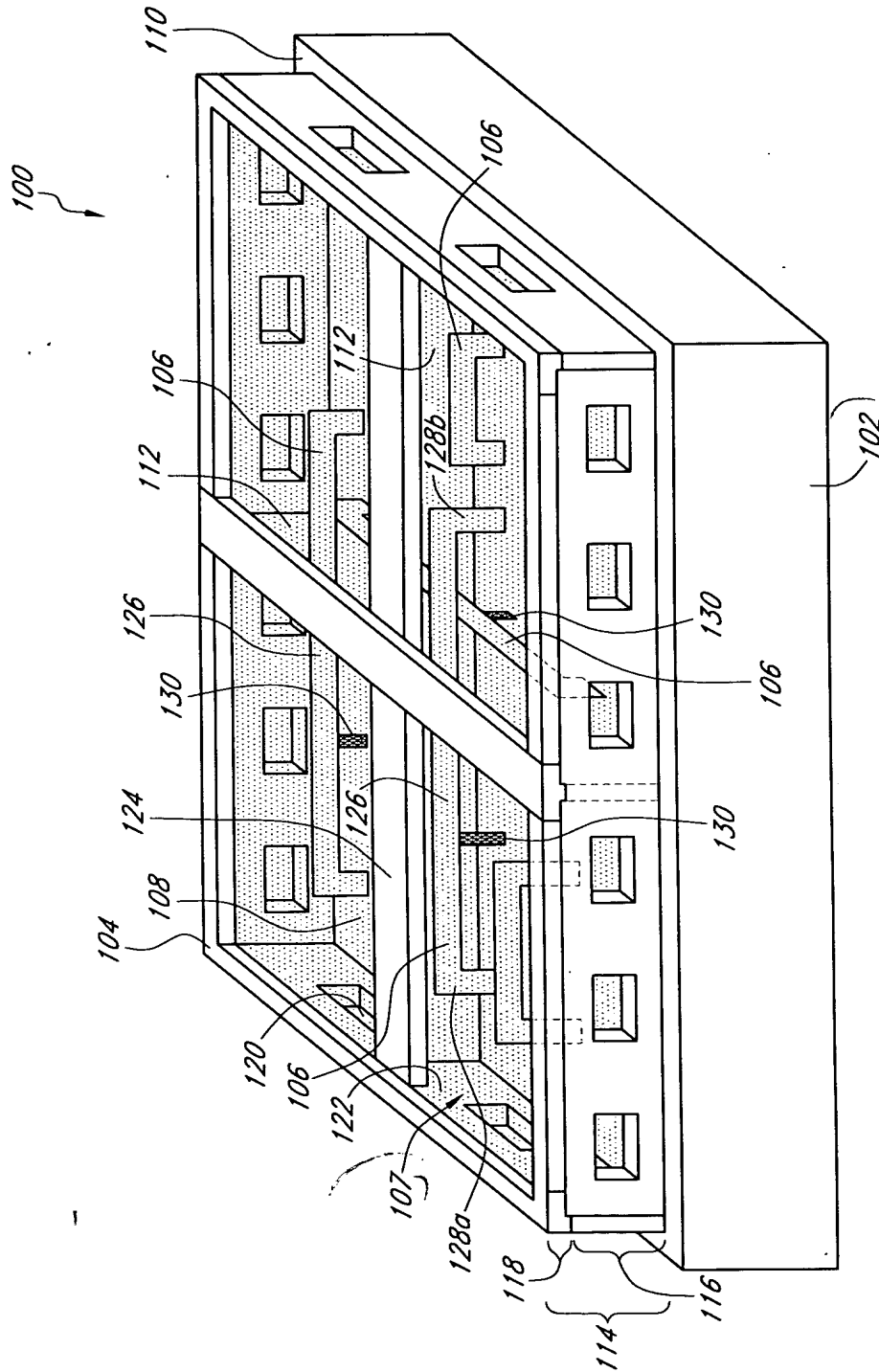


FIG. 1

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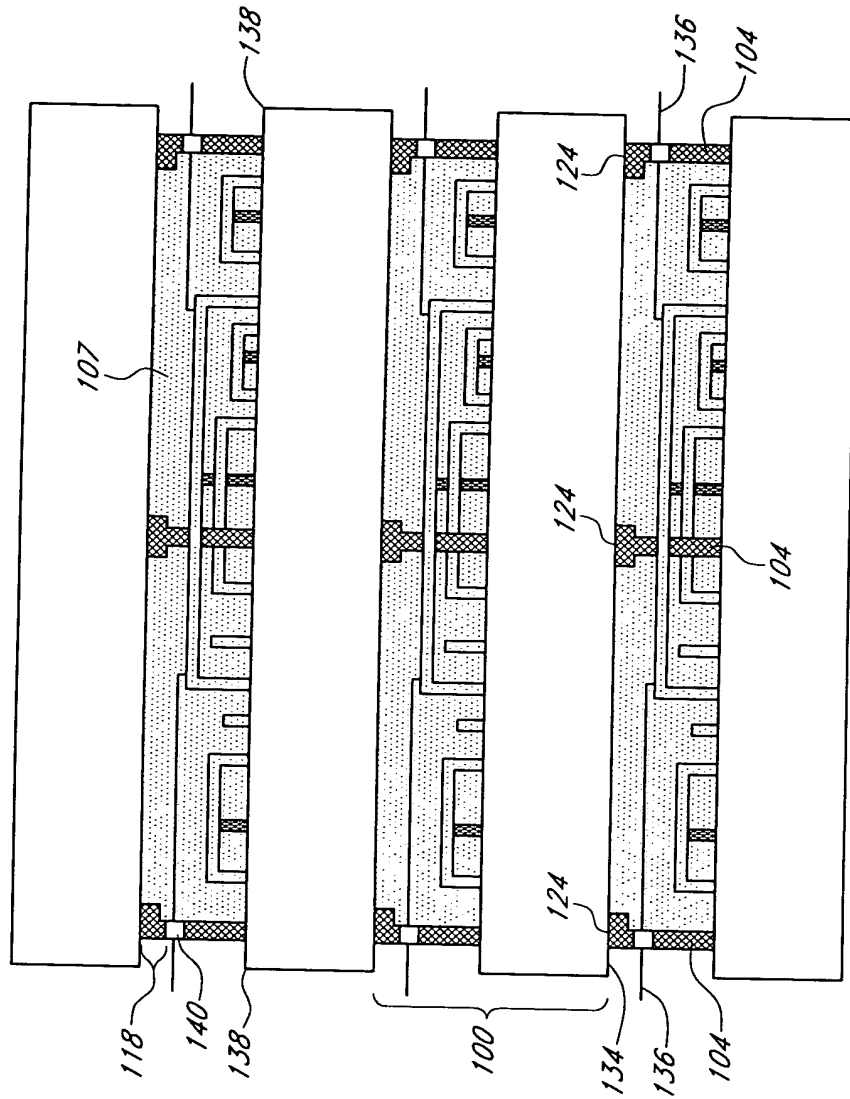


FIG. 2



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FIG. 4

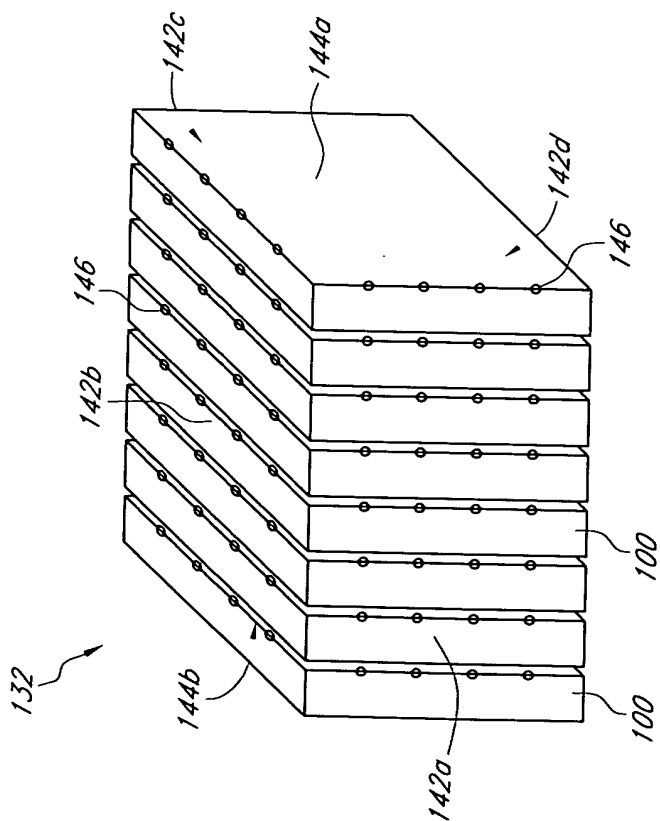
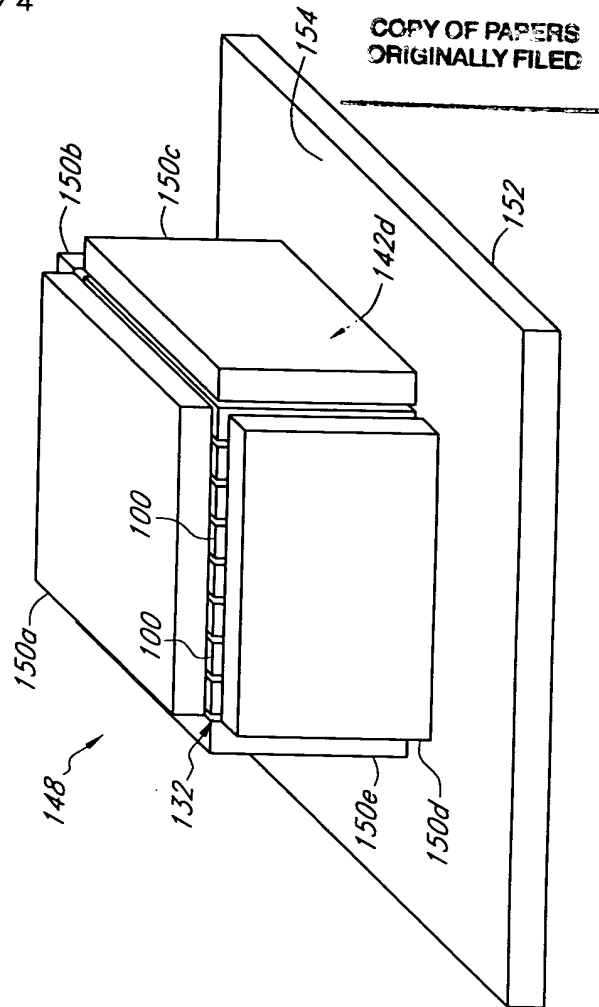


FIG. 3



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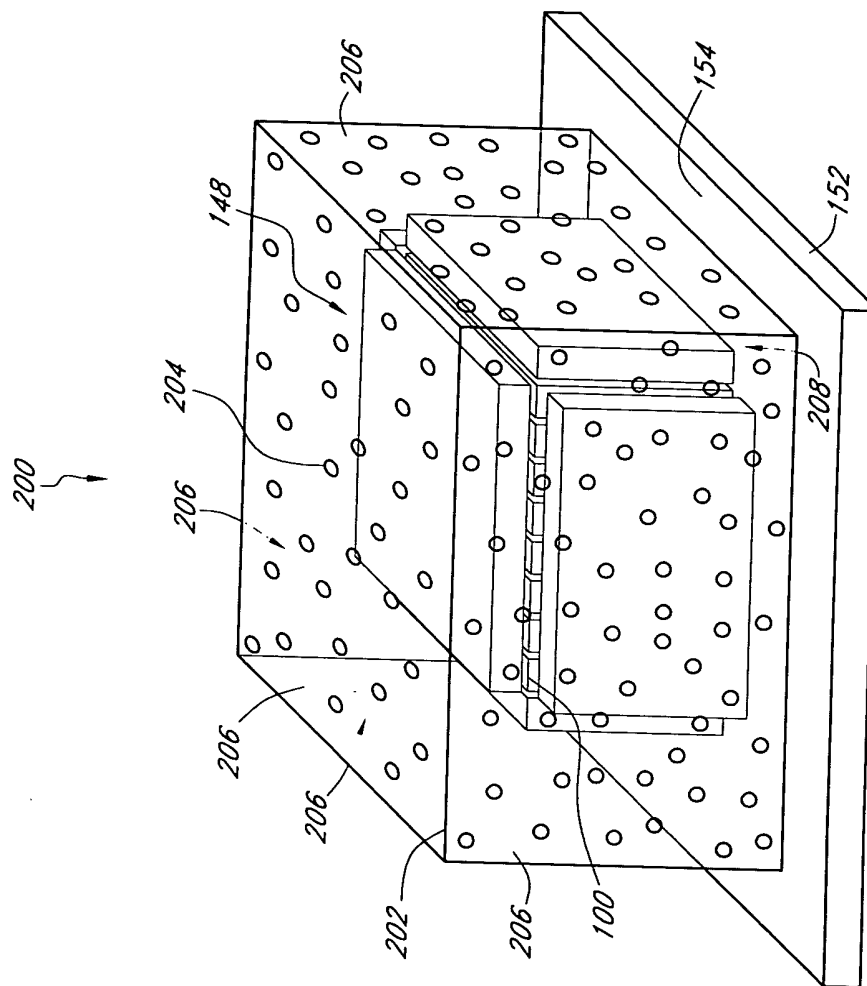


FIG. 5